

Title (en)  
ELECTRONIC DEVICE WITH HEAT CONDUCTIVE ENCASING DEVICE

Title (de)  
BRAUSEKOPF FÜR EINE SANITARBRAUSE

Title (fr)  
DISPOSITIF ELECTRONIQUE AVEC ENCAPSULANT THERMIQUEMENT CONDUCTEUR

Publication  
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Application  
**EP 01984192 A 20010706**

Priority  
• FR 0102187 W 20010706  
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Abstract (en)  
[origin: WO0205346A1] The invention concerns the field of electronic devices with heat conductive encasing device for eliminating part of the energy dissipated by the electronic components contained in the electronic device. It consists in a device comprising: a circuit (7) whereon are arranged several electronic components (8) capable of dissipating energy; a heat conductive cover (1) located opposite the circuit (7); a heat conductive encasing device (4) arranged between the circuit (7) and the cover (1) so as to ensure heat transfer, by conduction towards the cover (1), of the energy dissipated at the components (8); the respective surfaces of the encasing device (4) and of the cover (1) which are mutually opposite comprising an assembly of substantially matching recesses (3, 6) and protrusions (2, 5) for nesting the cover (1) and the encasing device (4), and clearances (j1, j2) are provided between the recesses (3, 6) and protrusions (2, 5) so as to reduce the load exerted by the cover (1) on the encasing device (4) towards the circuit (7) and for maintaining heat conduction between the encasing device (4) and the cover (1) at a level higher than a given conduction threshold. The invention can in particular be used for digital electronic cards.

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IPC 8 full level  
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